

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 11 December 2012 [Approved on 10 June 2016, 11:58 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.43000%	Gold	7440-57-5	1.50000%
			Silicon dioxide	14808-60-7	5.05000%
			Silicon	7440-21-3	93.45000%
Die attach	Lead and Lead alloys	0.24000%	Silver	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	EP (Epoxy resin)	49.04000%	Carbon black	1333-86-4	0.30000%
			ANTIMONY TRIOXIDE	1309-64-4	0.80000%
			3,3',4,4'-Tetrabromobisphenol A (TBBA)	79-94-7	0.99000%
			Epoxy resin 89	26335-32-0	27.61000%
			Quartz silica	14808-60-7	70.30000%
Leadfinish	Tin plating	0.51000%	Copper	7440-50-8	0.50000%
			Nickel	8049-31-8	0.60000%
			Silver	7440-22-4	3.00000%
			Tin	7440-31-5	95.90000%
Leadframe	Copper alloys	49.78000%	iron	14127-53-8	2.00000%
			Copper	7440-50-8	98.00000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DBIxx-xxX	Bridge Rectifier Three phase	9	g